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PART NO.	CODE NO.	NUMBER OF CONTACT	DIMENSION OF CONNECTOR. PCB MOUNTING PATTERN. STENCIL PATTERN AND FFC/FPC					DIMENSION OF DRAWING FOR PACKING							
			А	В	С	D	Е	F	G (1,6	J	К	L	М	N
FH40-10S-0.5SV	CL580-2104-6	10	5.57	8.2	4.5	5.5	7.1	16	CHI	7.5	8.4	5.2	17.4	21.4	3.5
FH40-20S-0.5SV	CL580-2105-9	20	10.57	13.2	9.5	10.5	12.1	24	/	11.5	13.4	10.2	25.4	29.4	6
FH40-24S-0.5SV	CL580-2106-1	24	12.57	15.2	11.5	12.5	14.1	24		11.5	15.4	12.2	25.4	29.4	6
FH40-30S-0.5SV	CL580-2108-7	30	15.57	18.2	14.5	15.5	17.1	32	28.4	14.2	18.4	15.2	33.4	37.4	6
FH40-40S-0.5SV	CL580-2107-4	40	20.57	23.2	19.5	20.5	22.1	44	40.4	20.2	23.4	20.2	45.4	49.4	6
FH40-45S-0.5SV	CL580-2101-8	45	23.07	25.7	22	23	24.6	44	40.4	20.2	25.9	22.7	45.4	49.4	6
FH40-50S-0.5SV	CL580-2100-5	50	25.57	28.2	24.5	25.5	27.1	44	40.4	20.2	28.4	25.2	45.4	49.4	6
FH40-60S-0.5SV	CL580-2109-0	60	30.57	33.2	29.5	30.5	32.1	56	52.4	26.2	33.4	30.2	57.4	61.4	6
FH40-64S-0.5SV	CL580-2102-0	64	32.57	35. 2	31.5	32.5	34.1	56	52.4	26.2	35.4	32.2	57.4	61.4	6
FH40-80S-0.5SV	CL580-2103-3	80	40.57	43.2	39.5	40.5	42.1	56	52.4	26, 2	43.4	40.2	57.4	61.4	8

| TRAWING | EDC-159298-00-05 | | PART | NO. | FH40-**S-0.5SV | CDE | NO. | CL580 | 2 5 9

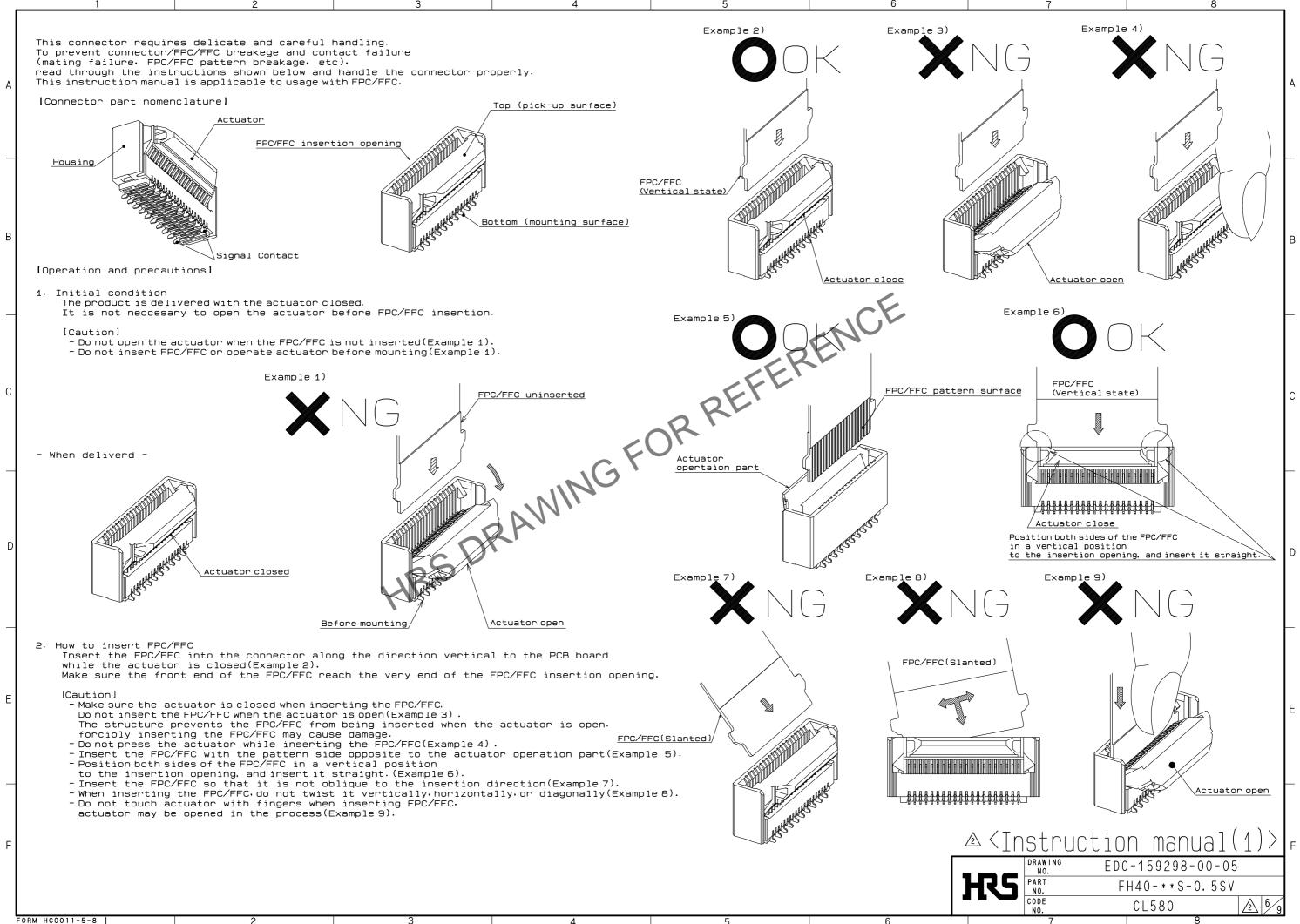
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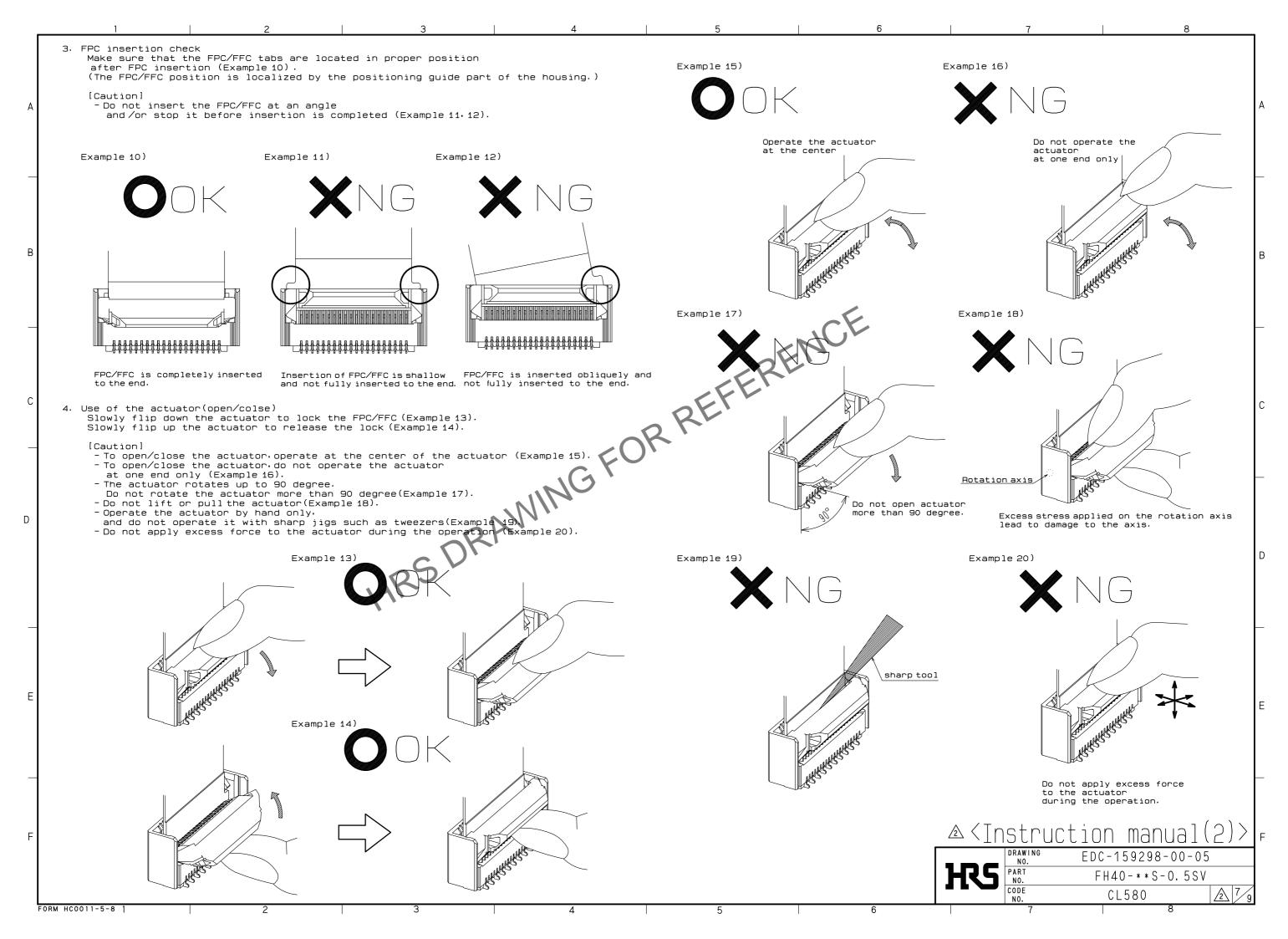
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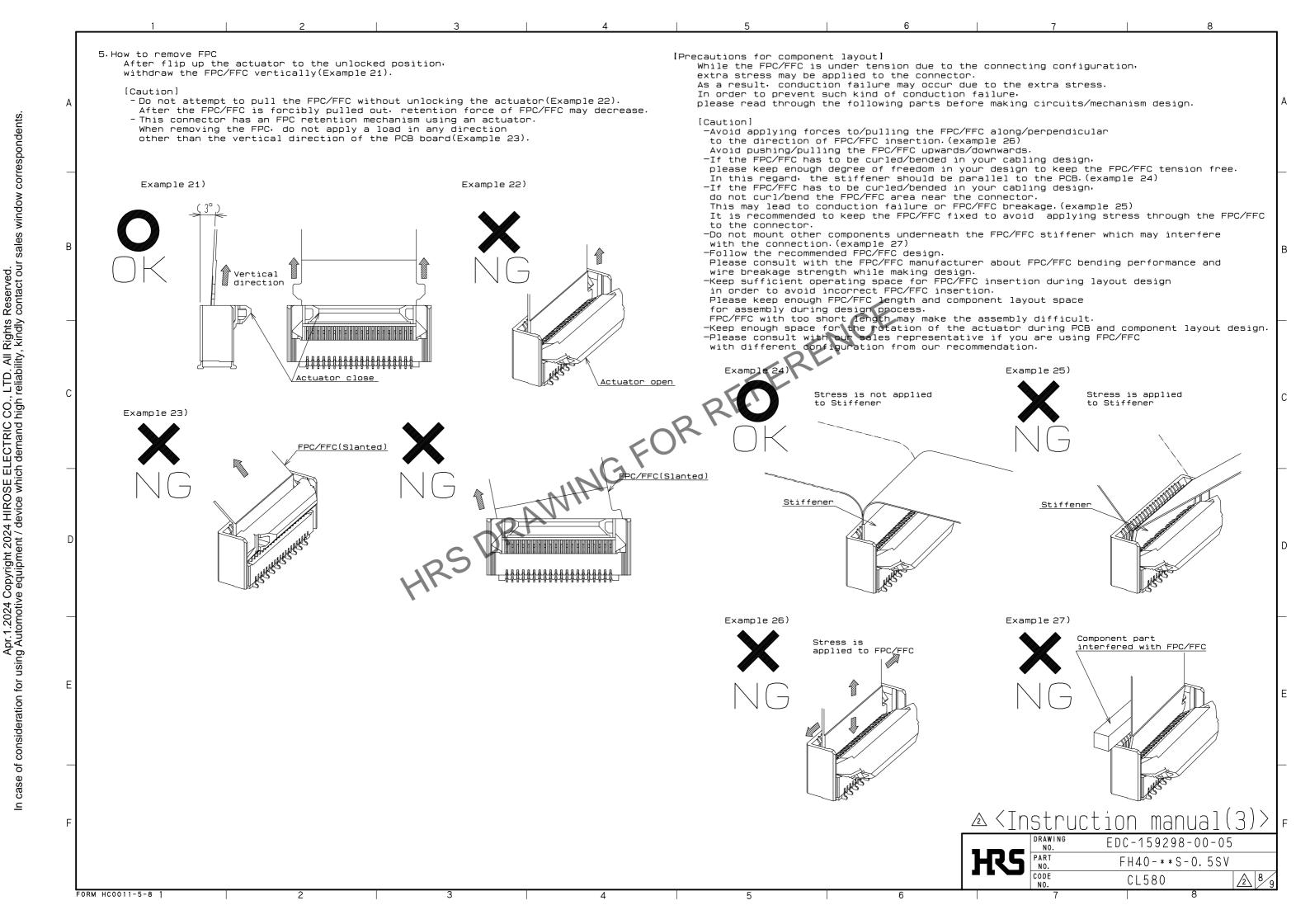
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FORM HC0011-5-8 1 2 3 4 5









FORM HC0011-5-8 1

| Instructions for mounting on the PCB| [Recommended reflow temperature profile] Follow the instructions shown below when mounting on the PCB. MAX 250 °C —Refer to recommended layouts on page 1 for PCB and stencil pattern. —Using either narrower land pattern or wider stencil pattern than recommendation may end up with excessive amount of solder/flux climbing on contact.

Please inspect the size of solder fillet and flux climbing height of the mounted connector while using different land/stencil pattern from our recommendation.

—Clearance between the mountage surface of the connector contact lead and the bottom of the housing is 230℃ 230 200°C 200 \sim very small. Solder resist/silk screening applied underneath the connector may interfere with the connector. This may lead to soldering defect/insufficient fillet formation.

Please verify your solder resist/silk screening design carefully before implementing the design. $\dot{\Omega}$ $\overline{}$ -Apply reflow temperature profile within the specified conditions. EMPERATURE For specific applications, the recommended temperature may vary depending on 150℃ type/ volume/thickness of solder paste and size/thickness of PCB. Please consult with your solder paste and equipment manufacturer for specific recommendations. -Please try to minimize the warpage of the PCB. Soldering failure could still occur due to the PCB warpage even if the coplanarity of the connecter is under 0.1mm. −If the connector is mounting on FPC/FFC please make sure to put a stiffener 100 on the backside of the FPC/FFC. Recommended stiffner: Glass epoxy material with thickness of 0.3 mm MIN. —Do not apply 1 N or greater external force on the connector when unreeling or handling the connector before mounting. Excessive mechanical stress may damage the connector before mounting. REFERENC25 | Instructions for PCB handling after mounting the connector | Follow the instructions shown below when mounting on the PCB. [Caution] MAX 60 sec. 90∼120 sec. - Splitting a large PCB into several pieces
- Installing mounting screw on PCB During the assembly processes described above, care shall be taken so as not to give any stresses of deflection or twisting to the PCB. Stresses applied on PCB may damage the connector as well

-The warpage of a 100 mm wide PCB should remain within 0.5 mm. (example 27) PRE-HEATING TIME SOLDERING TIME TIME (sec.) The warpage of a 100 mm wide PCB should remain within 0.5 mm. (example 27)

The warpage of PCB may apply excessive stress on the connector and damage the connector.

-Please perform conduction check with caution. Conductivity probe may damage the connector contacts.

-Attachment of foreign particles with the connector contact may lead to conduction failure.

In this particular case, the conduction failure may be fixed by re-inserting the FPC/FFC. Reflow method:IR reflow Number of reflow cycles:2 cycles MAX. 1)Reflow time Duration above 230°, 60 sec MAX. (Peak temperature:250℃ MAX) Example 27) 2)Pre-heat time 100 Pre−heat temperature(MIN):150℃ Pre-heat temperature(MAX):200℃ Connector Pre-heat time:90-120 sec. Connector MAX 100 | Instructions on manual soldering | Follow the instructions shown below when soldering the connector manually during repair work, etc. - Do not perform manual soldering with the FPC inserted into the connector. -Do not heat the connector excessively. Be very careful not to let the soldering iron contact any parts other than connector leads. Otherwise, the connector may be deformed or melt. - Do not supply excessive solder (or flux). If excessive solder (or flux) is supplied on the contact lead, solder or flux may adhere to the contact point, resulting in contaction failure . △ < Instruction manual DRAWING EDC-159298-00-05 FH40-**S-0.5SV 2 9 0 CL580

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